

IN THE SPECIFICATION:

At page 7, line 5, change the paragraph to read as follows:

Referring to Fig. 1, a multi-chip package which is designated as a Device Under Test 28, is seen connected to a test socket 30. The test socket 30 is connected to a digital multimeter 12 in order to monitor the resistance between two connections of the Device Under Test.

At page 7, lin 15, change the paragraph to read as follows:

A²

Placed upon the Device Under Test is an aluminum temperature Transfer Block 26, which is connected to a temperature meter 14 which can read the temperature of the aluminum temperature Transfer Block. Above, connected directly to the aluminum temperature Transfer Block, is a Peltier Thermal Electric Module 24 which is connected and regulated by a programmable power supply 16 controlled by the computer 10. Then, a heat sink 22 connects adjacent to the Peltier Thermal Electric Module and is supplied with a fan unit 20 which is controlled by a computer-controlled fan power supply 18.

At pag 8, line 9, change th paragraph to read as follows:

A Thermal Electric Module is a small solid-state device that can operate as a heat pump or as an electrical power generator. When used to generate electricity, the module is called a "Thermal Electric Generator" (TEG). wWhen used as a heat pump, the module utilizes the Peltier effect to remove move heat and is called a "Thermal Electric Cooler" (TEC).

a4

At page 9 line 34, and page 10 line 1, change the paragraph to read as follows:

Then the lower drawing in Fig. 2A shows an excessive amount of conductive epoxy 29ex having been applied to the end terminal metallic surfaces with the result of a spreading of the epoxy in an excessive manner thus causing in a short circuit of the internal component which in this case is illustrated as a capacitor. When this occurs, this particular surface mount component will be unable to serve its purpose and the epoxy short will overheat and may even burst into flame.

At page 10, line 31, change the paragraph to read as follows:

Then there are other components attached or connected to the power bus voltage and these are illustrated as specialized mounted components 29a, 39a, and 49a. In the illustration of Fig. 2B, these components are shown as capacitative elements wherein a capacitance is provided from the power bus 40 to the ground connection 42. Then for illustrative purposes, the component 29a is shown to have conductive epoxy 29x connected to the terminal pads 29b and 29c. The conductive epoxy 29x provides the electrical connection and mechanical holding connection of the component to the terminal pads 29b and 29c. However, should there be a spread of epoxy between the terminal pad 29b and 29c then, of course, there is a short circuit involved which will obviate the effect of the internal capacitance and nullify the action of the multi-chip package. Likewise, component 39a has epoxy 39x on terminal pads 39b and 39c; component 49a has epoxy 49x on terminal pads 49b and 49c.

At page 12, lin 13, change the paragraph to read as follows:

(a) Of course, while this is happening, the test that circuit 30 socket connected to multimeter 12 then reads out the ohms of resistance between the power bus and ground related to the particular component of the multi-chip module which is under test.

At page 13, lin 2, change the paragraph to read as follows:

a7 During the test, the Vcc to ground resistance is constantly monitored along with a temperature change. These parameters are then plotted on the computer monitor screen for evaluation and also at the same time a report is saved in a file for future reference.

At page 13, line 26, change the paragraph to read as follows:

The fan 20 is used to help the thermal electric module 24 maintain room temperature on the external side for faster response. The heat sink 22 is used to help the fan do a faster temperature transfer, that is to say, provide air to the thermal electric module and then vent the thermal electric module to air.

as

At page 18, lin 6, change the paragraph to read as follows:

(u)9

Then Fig. 5A-6A shows step N indicating termination of the test and need to remove the DUT 28. A signal is then sent to step A to check the Transfer Block temperature in order to verify it is then at the room temperature, and ready for another DUT to be tested.